

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S49	17	(ic chip) with active near2 circuit and (redistribut\$3 metal) near2 layer and polyimide with etch\$3	USPAT; EPO; JPO	OR	ON	2005/06/17 14:20
S50	25	active near2 circuit and (redistribut\$3 metal) near2 layer and polyimide with etch\$3 and solder\$3 near3 (ball bump)	USPAT; EPO; JPO	OR	ON	2005/06/17 14:25
S51	1	438/612 and active near2 circuit and (redistribut\$3 metal\$3 conductive) near2 layer and polyimide with etch\$3 and solder\$3 near3 (ball bump)	USPAT; EPO; JPO	OR	ON	2005/06/17 14:29
S52	8	"438"/\$ and active near2 circuit and (redistribut\$3 metal\$3 conductive) near2 layer and polyimide with etch\$3 and solder\$3 near3 (ball bump)	USPAT; EPO; JPO	OR	ON	2005/06/17 14:30
S53	20	"257"/\$ and active near2 circuit and (redistribut\$3 metal\$3 conductive) near2 layer and polyimide with etch\$3 and solder\$3 near3 (ball bump)	USPAT; EPO; JPO	OR	ON	2005/06/17 14:30
S54	13	"29"/\$ and active near2 circuit and (redistribut\$3 metal\$3 conductive) near2 layer and polyimide with etch\$3 and solder\$3 near3 (ball bump)	USPAT; EPO; JPO	OR	ON	2005/06/17 14:31
S55	101	active near2 circuit and (redistribut\$3 metal\$3 conductive) near2 layer and polyimide with etch\$3	USPAT; EPO; JPO	OR	ON	2005/06/17 14:42
S56	57	active near2 (area circuit) and (redistribut\$3 metal\$3 conductive) near2 layer and polyimide with etch\$3 and solder\$3 with (bump ball)	USPAT; EPO; JPO	OR	ON	2005/06/17 15:20
S57	75	active near2 (area circuit layer) and (redistribut\$3 metal\$3 conductive) near2 layer and polyimide with etch\$3 and solder\$3 with (bump ball)	USPAT; EPO; JPO	OR	ON	2005/06/17 16:31
S58	3	("6000130" "6033984" "6479900").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 16:23
S59	76	active near2 (area circuit layer) and (redistribut\$3 metal\$3 conductive wiring) near2 layer and polyimide with etch\$3 and solder\$3 with (bump ball)	USPAT; EPO; JPO	OR	ON	2005/06/17 18:29

S60	76	S59 not S58	USPAT; EPO; JPO	OR	ON	2005/06/17 16:46
S61	1	S59 not S57	USPAT; EPO; JPO	OR	ON	2005/06/17 16:46
S62	3	("6000130" "6033984" "6479900").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 16:47
S63	3	("5976710" "6103552" "6111317").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 16:47
S64	89	active near2 (area circuit layer element) and (redistribut\$3 metal\$3 conductive wiring) near2 layer and polyimide with etch\$3 and solder\$3 with (bump ball)	USPAT; EPO; JPO	OR	ON	2005/06/17 18:30
S65	88	S64 not S61	USPAT; EPO; JPO	OR	ON	2005/06/17 18:31
S66	13	S64 not S60	USPAT; EPO; JPO	OR	ON	2005/06/17 18:31